

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

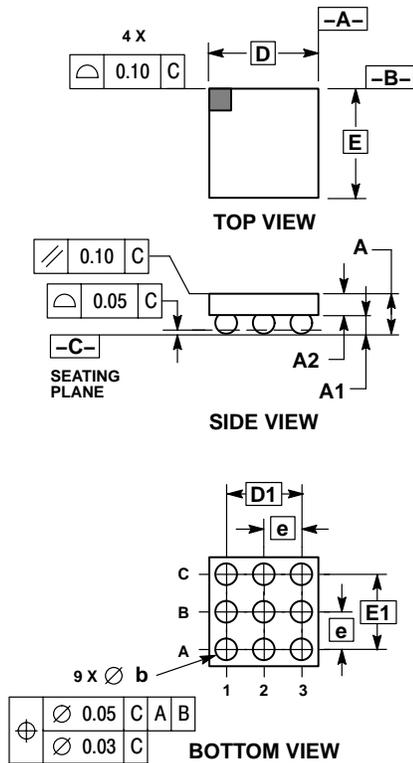


9 PIN FLIP-CHIP CASE 499E-01 ISSUE A

DATE 30 JUN 2004



SCALE 4:1

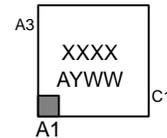


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	0.540	0.660
A1	0.210	0.270
A2	0.330	0.390
D	1.450 BSC	
E	1.450 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	1.000 BSC	
E1	1.000 BSC	

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	9 PIN FLIP-CHIP, 1.45 X 1.45 MM	PAGE 1 OF 2

